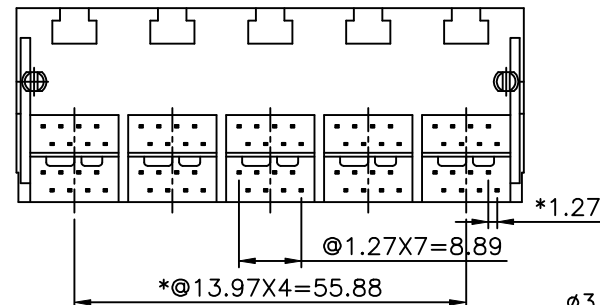
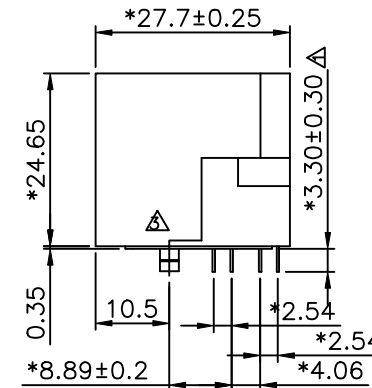
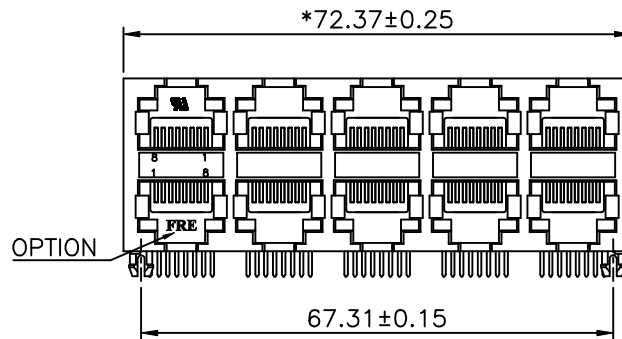


REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD
①		EC DIM	Ming-Wei 04/15/02	
②		ADD PART NO.	Glanpu 6/19/04	
③		MODIFY DRAWING	QIULER 12/03/04	
④		MODIFY DRAWING	QIULER 01/25/05	



NOTES:

ELECTRICAL:

1. VOLTAGE RATING : 125 VAC RMS.
2. CURRENT RATING : 1.5 AMP.
3. CONTACT RESISTANCE : 50 MILLIOHMS MAX.
4. INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500 VDC.
5. DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.

MECHANICAL:

1. HOUSING MATERIAL : GLASS FILLED POLYESTER UL94V-0.
2. CONTACT MATERIAL : PHOSPHOR BRONZE t=0.35mm.
3. PLATING : GOLD PLATING OVER NICKEL.
4. OPERATING LIFE : 750 CYCLES MIN.
5. PCB RETENTION PRE-SOLDER : 1 LB MIN.
6. PCB RETENTION POST-SOLDER: 10 LBS MIN.

ENVIRONMENTAL:

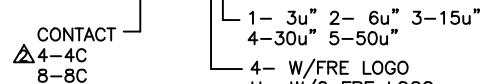
1. STORAGE : -40°C TO $+85^{\circ}\text{C}$.
2. OPERATION: 0°C TO 70°C .

MATES WITH MODULAR PLUG CONFORMING TO

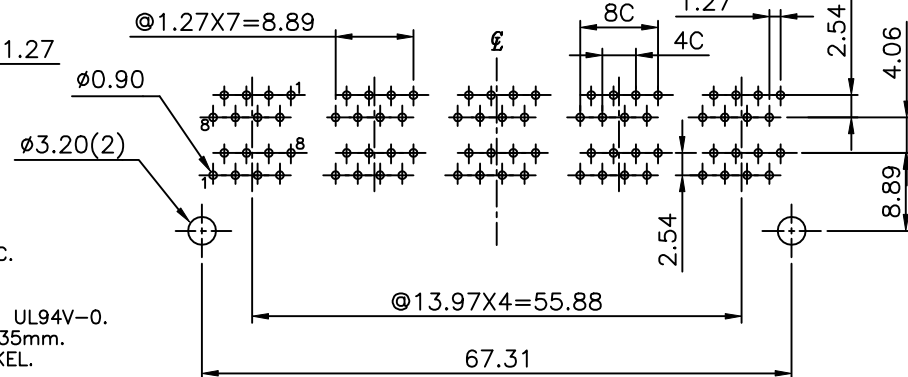
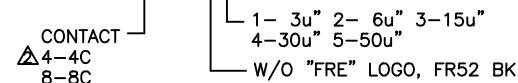
FCC PART 68, SUBPART F.

CUL FILE NO. 163191

PART NUMBER: E590X-0TDOXX



④ LEAD FREE PART NUMBER: E590X-0TDYUX-L



PC Board Layout Component Side Shown

PC Board Thickness=1.6mm

DETACHED LISTS			DFTO Ming-Wei		DATE 04/09/2002		FULL RISE ELECTRONIC CO., LTD			
	TOLERANCES EXCEPT AS NOTED		CHKD GANPU		DATE 2006/1/28					
	MM		MFO		DATE		TITLE STAMPED PIN III STACKED GANGED JACK, 2X5			
	.0 ±0.2		APPVLU SHENG		DATE 2005/1/28					
	.00 ±0.15		MATERIAL :				DRAWING NO. GE593B55 /PART NO. SEE NOTE SIZE A3 REV 4			
	.000 ±0.075									
	ANGLES ± 0.5		QT'Y :		FINISH :		SCALE : 1.5 : 1 DO NOT SCALE DRAWING SHEET 1 OF 1			
			THIRD ANGLE PROJECTION							